

# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Application No.	10/822,424
Filing Date	April 12, 2004
First Named Inventor	Bulent M. Basol
Art Unit	<del>1742</del> 1795
Examiner	Zulmariam Mendez
Attorney Docket No.	NVLUS.029CP1(5296)

(Multiple sheets used when necessary)

SHEET 1 OF 2

## U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
/Z.M./	1	5,553,527	09-10-1996	Harrison	
/Z.M./	2	5,660,708	08-26-1997	Tezuka et al.	
/Z.M./	3	6,582,281	06-24-2003	Doan et al.	

## FOREIGN PATENT DOCUMENTS

Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T <sup>1</sup>
/Z.M./	4	DE 2008664	09-09-1971	Jostan		
	5	DE 4324330	03-02-1994	Schneider		
	6	FR 2763343	05-13-1998	Reidsema et al.		
	7	GB 1350070	04-18-1974	Luttmer et al.		
	8	JP 6-108285	04-22-1994	Ezawa et al.		
	9	JP 11-054479	02-26-1999	Nakajima		
	10	WO 97/01657	01-16-1997	Billman		
	11	WO 98/27585	06-25-1998	Andricacos et al.		
	12	WO 99/64647	12-16-1999	Adams et al.		
	13	WO 00/03426	01-20-2000	Wang et al.		
	14	WO 00/26443	05-11-2000	Talieh		
/Z.M./	15	WO 02/064314	08-22-2002	Emesh et al.		

## NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>1</sup>
/Z.M./	16	Contolini et al., "Electrochemical Planarization for Multilevel Metallization," J. Electrochem. Soc., 1994, Vol. 141, pp. 2503-2510.	
/Z.M./	17	Kelly et al., "Leveling and Microstructural Effects of Additives for Copper Electrodeposition," J. Electrochem. Soc., 1999, Vol. 146, No. 7, pp. 2540-2545.	
/Z.M./	18	Madore et al., "Blocking inhibitors in Cathodic Leveling," <u>Theoretical Analysis</u> , December 1997, pp. 3927-3942.	
/Z.M./	19	Mikkola et al., "Investigation of the Roles of the Additive Components for Second Generation Copper Electroplating Chemistries Used for Advanced Interconnect Metallization," 2000 IEEE, June 2000, pp. 117-119, IEEE Electron Devices Society.	

Examiner Signature /Zulmariam Mendez/

Date Considered 10/28/2007

\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

T<sup>1</sup> - Place a check mark in this area when an English language Translation is attached.

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/Z.M./	20	Rubinstein, "Tampongalvanisieren in der Praxis, Teil 1," <u>Galvanotechnik</u> , 1988, Vol. 79, No. 10, pp. 3263-3270.	
/Z.M./	21	Joseph M. Steigerwald et al., "Chemical Mechanical Planarization of Microelectronic Materials," A Wiley-Interscience Publication, 1997 by John Wiley & Sons, Inc. pp 212-222.	
/Z.M./	22	Steigerwald et al., "Pattern Geometry Effects in the Chemical-Mechanical Polishing of Inlaid Copper Structures," J. Electrochem. Soc., 1994, Vol. 141, pp. 2842-2848.	
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<del>/Z.M./</del>	<del>24</del>	<del>Office Action for U.S. Patent Application No. 10/391,924, dated April 30, 2007</del>	
<del>/Z.M./</del>	<del>25</del>	<del>Response to Office Action for U.S. Patent Application No. 10/391,924, dated April 30, 2007</del>	

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